



US 20200035947A1

(19) **United States**

(12) **Patent Application Publication**  
**FUJIMORI et al.**

(10) **Pub. No.: US 2020/0035947 A1**  
(43) **Pub. Date: Jan. 30, 2020**

(54) **DISPLAY DEVICE**

*C23C 16/513* (2006.01)

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*C23C 16/34* (2006.01)

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(52) **U.S. Cl.**

*C23C 16/40* (2006.01)

CPC ..... *H01L 51/5253* (2013.01); *H01L 51/0097*  
(2013.01); *C23C 16/403* (2013.01); *C23C*  
*16/345* (2013.01); *C23C 16/402* (2013.01);  
*C23C 16/513* (2013.01)

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(21) Appl. No.: **16/521,699**

(57)

**ABSTRACT**

(22) Filed: **Jul. 25, 2019**

A light-emitting display device includes an element-formation substrate and a plurality of pixels. The element-formation substrate includes a first barrier film and a second barrier film provided on a substrate, the first barrier film and the second barrier film being provided in the stated order from the substrate and suppressing ingress of moisture. The plurality of pixels is provided on the element-formation substrate. The element-formation substrate further includes an organic part that fills a crack occurred in the first barrier film, or that is attached around a part of a metallic foreign substance protruding from the first barrier film.

(30) **Foreign Application Priority Data**

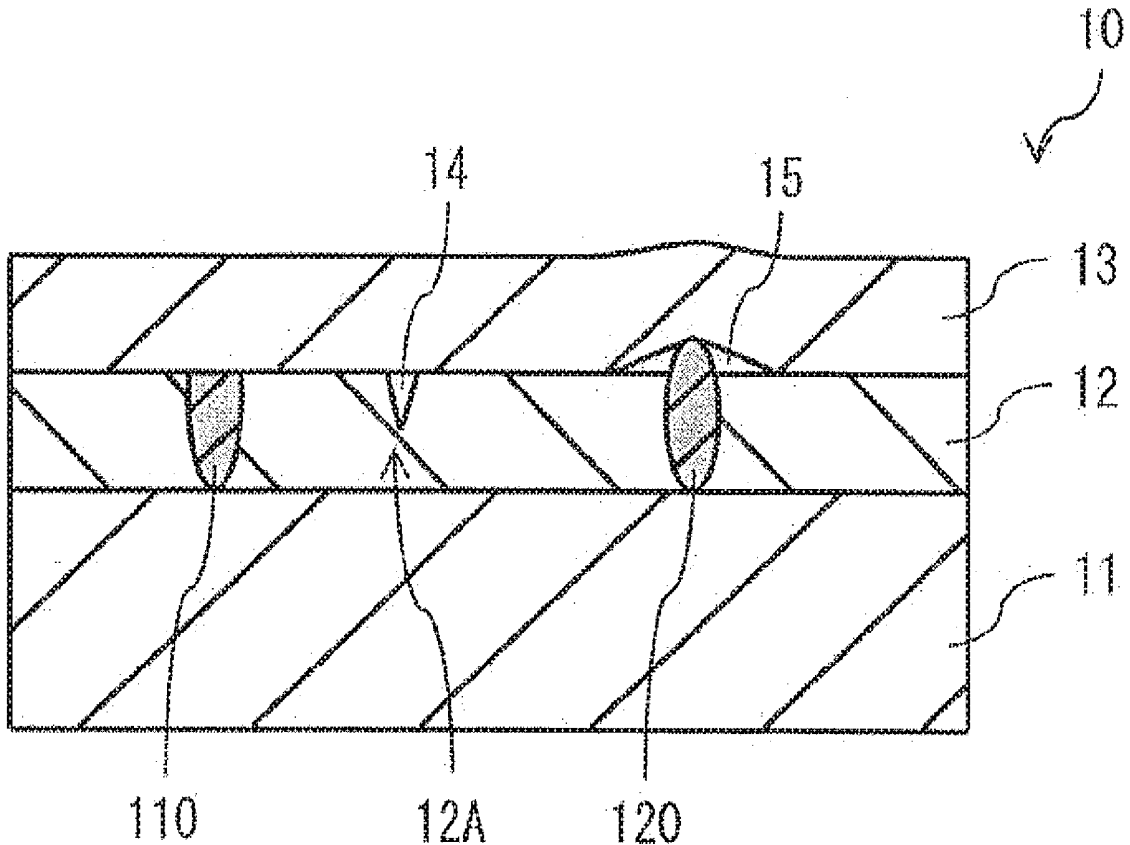
Jul. 27, 2018 (JP) ..... 2018-141797

**Publication Classification**

(51) **Int. Cl.**

*H01L 51/52* (2006.01)

*H01L 51/00* (2006.01)



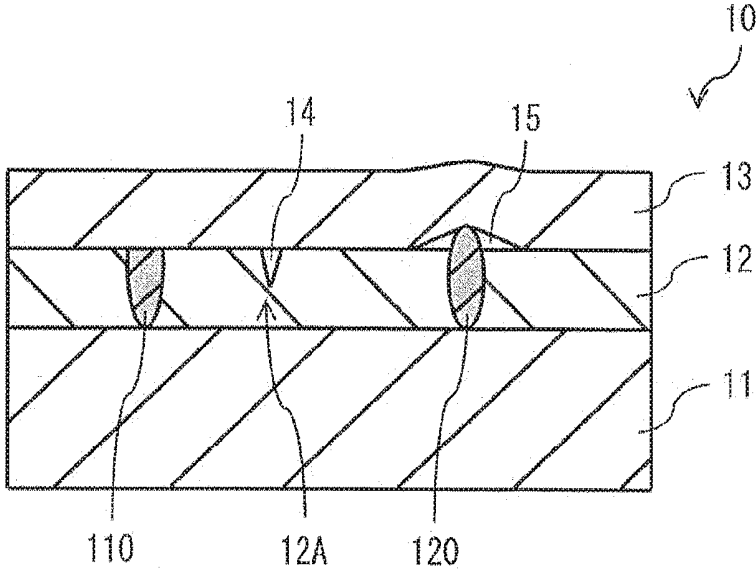


FIG. 1

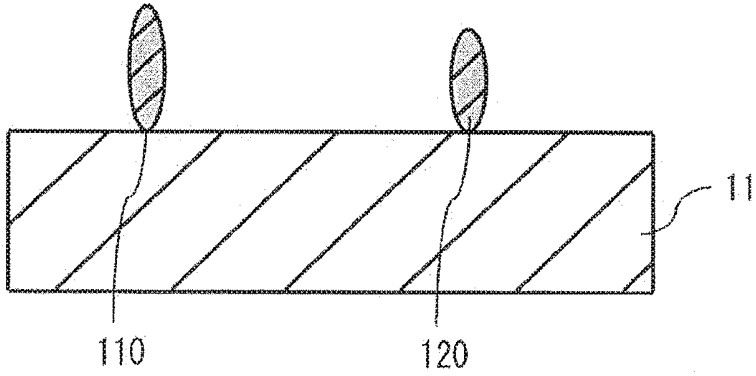


FIG. 2A

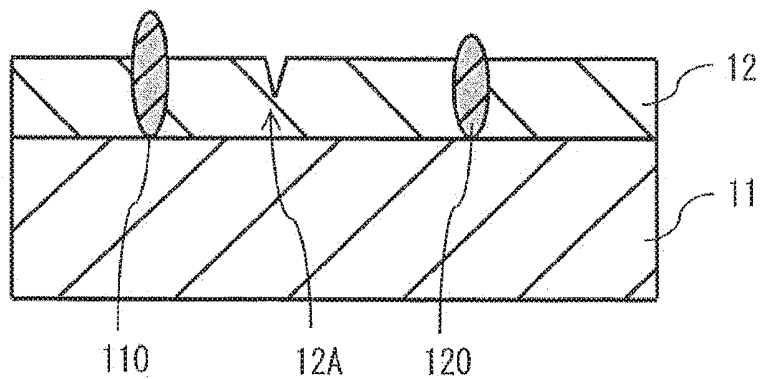


FIG. 2B

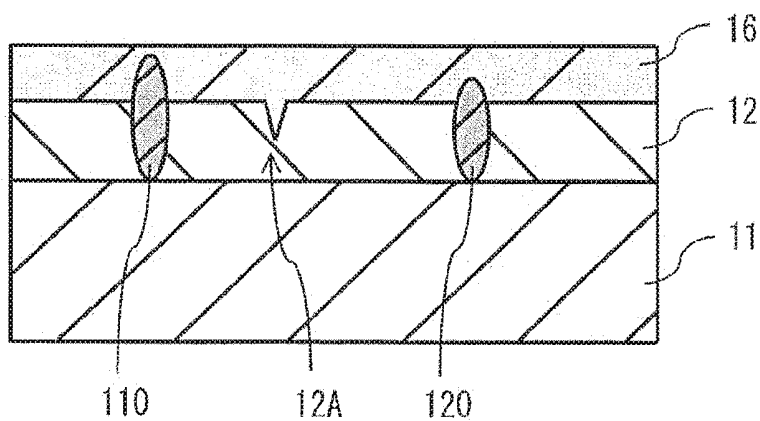


FIG. 2C

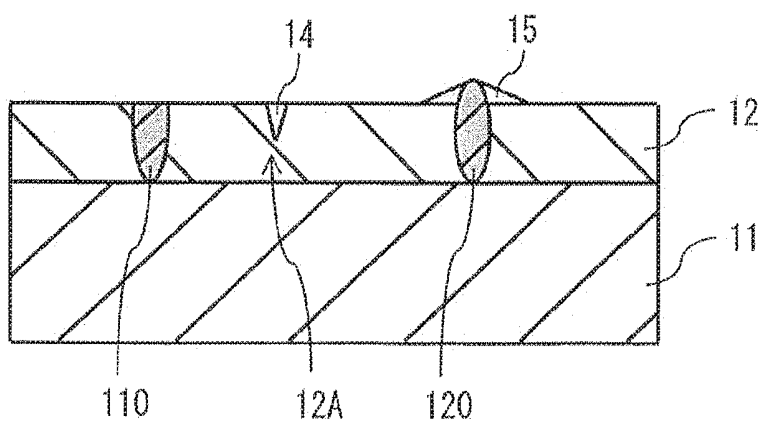


FIG. 2D

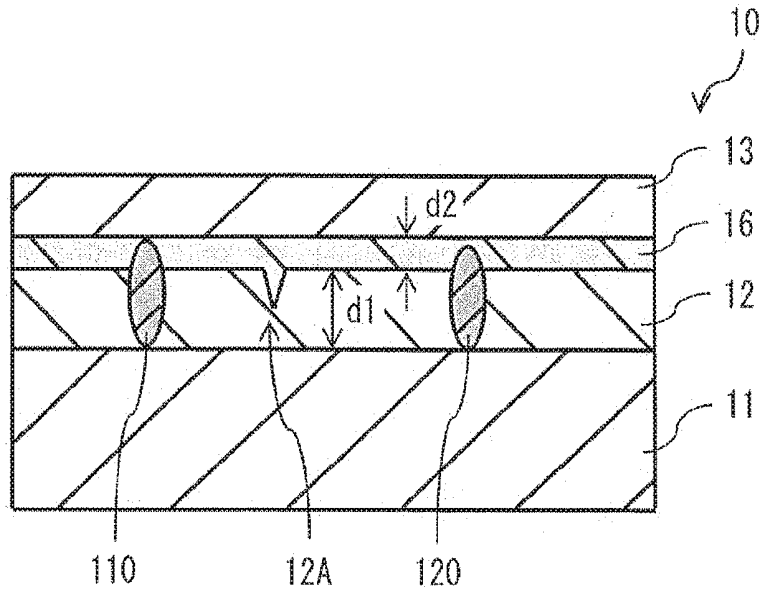


FIG. 3

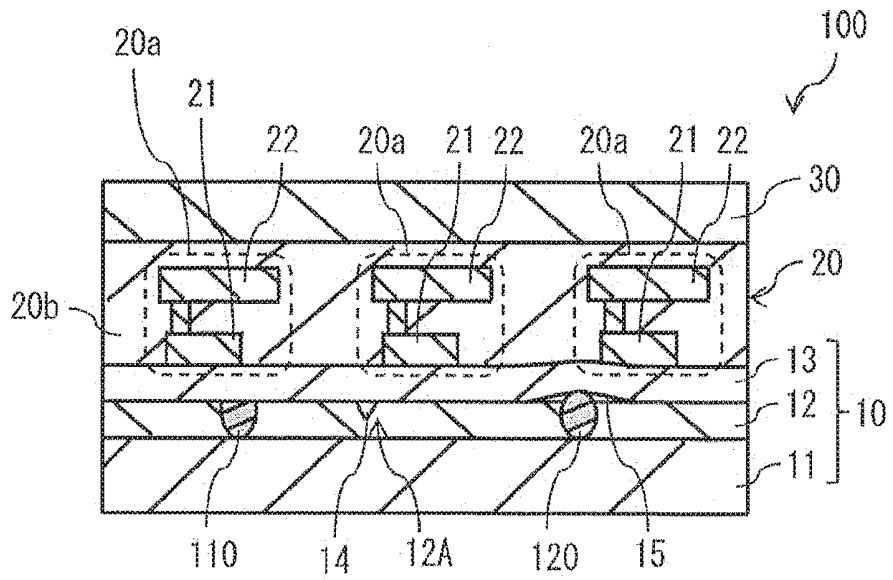


FIG. 4

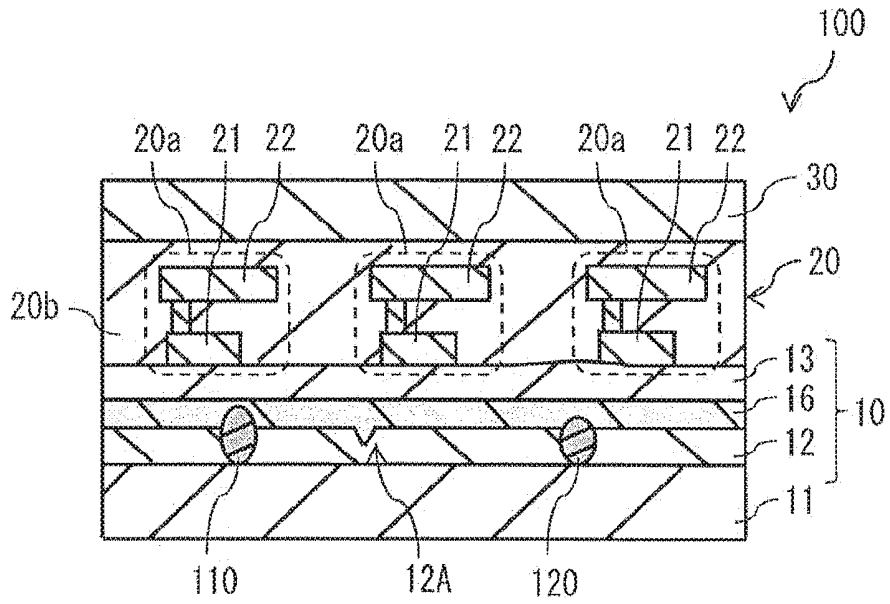


FIG. 5

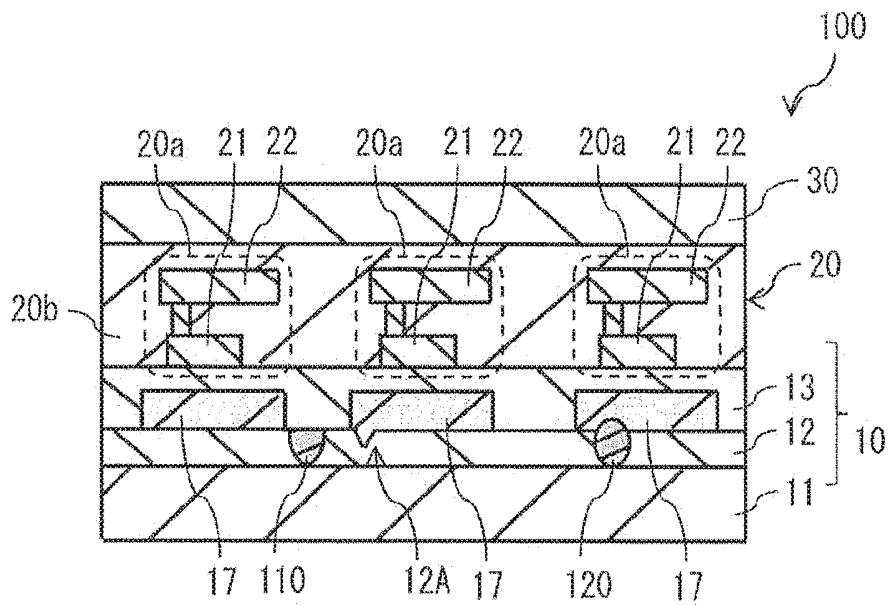


FIG. 6

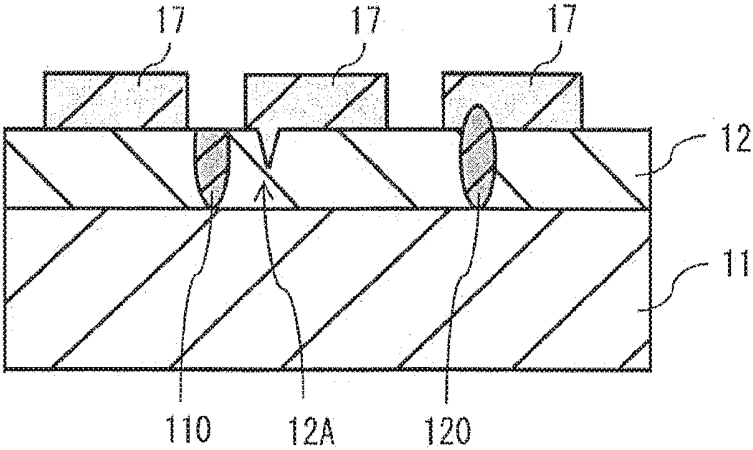


FIG. 7

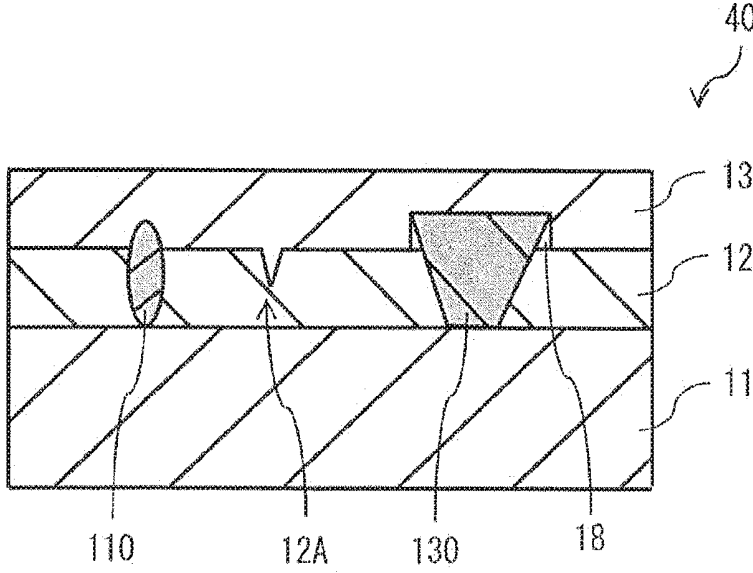


FIG. 8

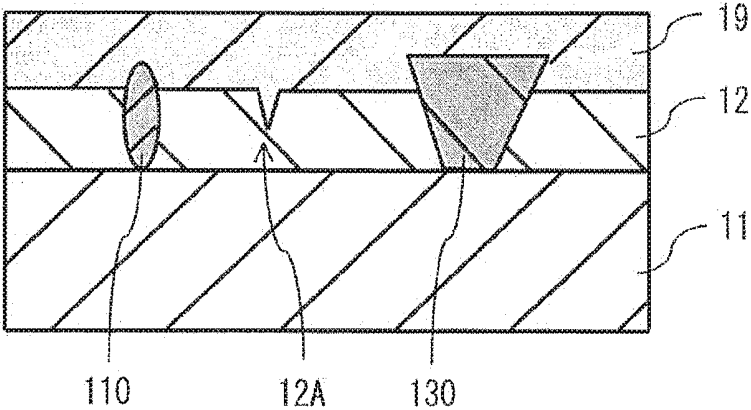


FIG. 9A

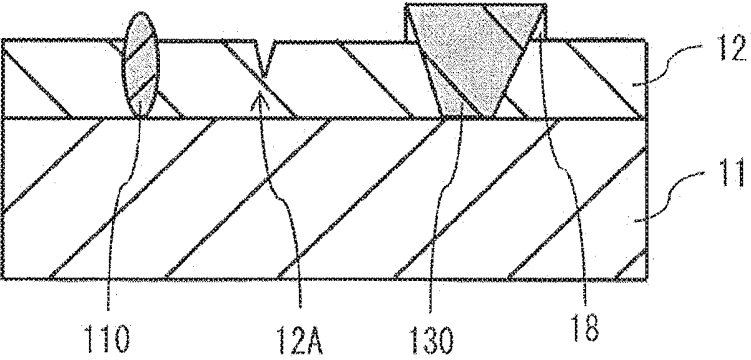


FIG. 9B

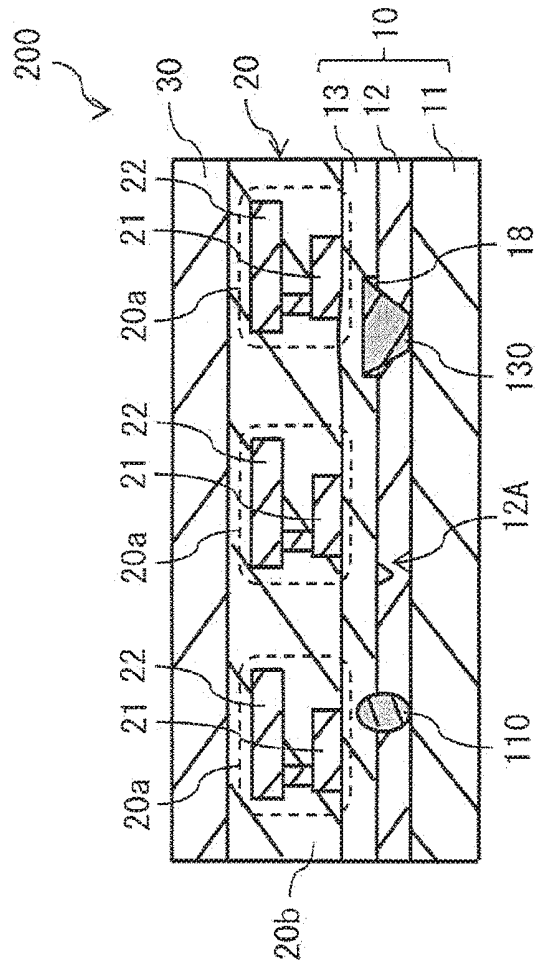


FIG. 10

## DISPLAY DEVICE

### CROSS REFERENCE TO RELATED APPLICATIONS

[0001] This application claims the benefit of Japanese Priority Patent Application No. 2018-141797 filed on Jul. 27, 2018, the entire contents of which are incorporated herein by reference.

### BACKGROUND

[0002] The disclosure relates to a light-emitting display device, and particularly relates to a light-emitting display device including a barrier film that includes an inorganic material which is provided on a substrate.

[0003] Typical examples of the light-emitting display device include an organic electroluminescence (EL) display element. In a light-emitting display device, a current flows in an organic compound included in a layer (hereinafter, referred to as EL layer) sandwiched between a pair of electrodes. Therefore, the organic compound is oxidized or reduced while the light-emitting element is driven, and may be in a state of being electrically-charged. Moreover, recombination of those active species results in an excited state. Those active species and molecules in the excited state are more reactive than molecules in an electrically neutral state or in the ground state, and thereby react with other organic compound or easily react with impurities, such as water or oxygen, that enter the light-emitting element. Such reactions adversely affect characteristics of the light-emitting element, and reduce efficiency and life of the light-emitting element. Accordingly, a display device is proposed that suppresses ingress of moisture into an organic EL element. Reference is made to Japanese Unexamined Patent Application Publication No. 2017-152188, for example.

### SUMMARY

[0004] There is a demand for a light-emitting display device that has further enhanced moisture resistance.

[0005] It is desired to provide a light-emitting display device that makes it possible to further enhance moisture resistance.

[0006] A method of manufacturing a light-emitting display device according to an example embodiment includes forming a first barrier film on a substrate, forming an organic layer on the first barrier film, and forming a second barrier film on a surface including the organic layer. The first barrier film suppresses ingress of moisture. The organic layer has a thickness smaller than a thickness of the substrate. The second barrier film suppresses ingress of moisture.

[0007] A light-emitting display device according to an example embodiment includes an element-formation substrate and a plurality of pixels. The element-formation substrate includes a first barrier film and a second barrier film provided on a substrate, the first barrier film and the second barrier film being provided in the stated order from the substrate and suppressing ingress of moisture. The plurality of pixels is provided on the element-formation substrate. The element-formation substrate further includes an organic part that fills a crack occurred in the first barrier film, or that is attached around a part of a metallic foreign substance, the part of the metallic foreign substance protruding from the first barrier film.

[0008] A light-emitting display device according to an example embodiment includes an element-formation substrate and a plurality of pixels. The element-formation substrate includes a first barrier film and a second barrier film provided on a substrate, the first barrier film and the second barrier film being provided in the stated order from the substrate and suppressing ingress of moisture. The plurality of pixels is provided on the element-formation substrate. The element-formation substrate includes an organic layer that fills a crack occurred in the first barrier film, or that covers a part of a metallic foreign substance, the part of the metallic foreign substance protruding from the first barrier film, the organic layer being provided between the first barrier film and the second barrier film.

### BRIEF DESCRIPTION OF THE DRAWINGS

[0009] The accompanying drawings are included to provide a further understanding of the disclosure and are incorporated in and constitute a part of this specification. The drawings illustrate example embodiments and, together with the specification, serve to explain the principles of the disclosure.

[0010] FIG. 1 is a diagram illustrating an example of a cross-sectional configuration of an element-formation substrate according to one example embodiment of the disclosure.

[0011] FIG. 2A is a diagram illustrating an example of a method of manufacturing the element-formation substrate illustrated in FIG. 1.

[0012] FIG. 2B is a diagram illustrating an example of a manufacturing process following the process illustrated in FIG. 2A.

[0013] FIG. 2C is a diagram illustrating an example of a manufacturing process following the process illustrated in FIG. 2B.

[0014] FIG. 2D is a diagram illustrating an example of a manufacturing process following the process illustrated in FIG. 2C.

[0015] FIG. 3 is a diagram illustrating a modification example of the cross-sectional configuration of the element-formation substrate illustrated in FIG. 1.

[0016] FIG. 4 is a diagram illustrating an example of a cross-sectional configuration of an organic EL panel including the element-formation substrate illustrated in FIG. 1.

[0017] FIG. 5 is a diagram illustrating a modification example of the cross-sectional configuration of the organic EL panel illustrated in FIG. 4.

[0018] FIG. 6 is a diagram illustrating a modification example of the cross-sectional configuration of the organic EL panel illustrated in FIG. 4.

[0019] FIG. 7 is a diagram illustrating an example of a method of manufacturing the element-formation substrate included in the organic EL panel illustrated in FIG. 6.

[0020] FIG. 8 is a diagram illustrating an example of a cross-sectional configuration of an element-formation substrate according to one example embodiment of the disclosure.

[0021] FIG. 9A is a diagram illustrating an example of a method of manufacturing the element-formation substrate illustrated in FIG. 8.

[0022] FIG. 9B is a diagram illustrating an example of a manufacturing process following the process illustrated in FIG. 9A.

[0023] FIG. 10 is a diagram illustrating an example of a cross-sectional configuration of an organic EL panel including the element-formation substrate illustrated in FIG. 8.

#### DETAILED DESCRIPTION

[0024] In the following, some example embodiments of the disclosure are described in detail, in the following order, with reference to the accompanying drawings. Note that the following description is directed to illustrative examples of the disclosure and not to be construed as limiting to the disclosure. Factors including, without limitation, numerical values, shapes, materials, components, positions of the components, and how the components are coupled to each other are illustrative only and not to be construed as limiting to the disclosure. Further, elements in the following example embodiments which are not recited in a most-generic independent claim of the disclosure are optional and may be provided on an as-needed basis. The drawings are schematic and are not intended to be drawn to scale. Note that the like elements are denoted with the same reference numerals, and any redundant description thereof will not be described in detail. Note that the description is given in the following order.

[0025] 1. First Embodiment (element-formation substrate, organic EL panel)

[0026] 2. Modification Example of First Embodiment (organic EL panel)

[0027] 3. Second Embodiment (element-formation substrate, organic EL panel)

##### 1. First Embodiment

[Configuration]

[0028] FIG. 1 is a diagram illustrating an example of a cross-sectional configuration of an element-formation substrate 10 according to one example embodiment of the disclosure. The element-formation substrate 10 may be suitably used as a substrate for forming an element easily influenced by moisture. The element mentioned herein refers to an element whose characteristics are easily degraded due to ingress of moisture. Non-limiting examples of the element easily influenced by moisture include an organic EL element and an active element including an oxide semiconductor or low-temperature polycrystalline silicon.

[0029] The element-formation substrate 10 is a substrate that has two barrier films 12 and 13 provided on a substrate 11. In one embodiment of the disclosure, the barrier film 12 corresponds to a specific but non-limiting example of a "first barrier film". In one embodiment of the disclosure, the barrier film 13 corresponds to a specific but non-limiting example of a "second barrier film". The substrate 11 may be a flexible substrate, which may include a resin substrate having flexibility. Non-limiting examples of the resin used for the substrate 11 may include plastics such as polyimide (PI), polyethylene terephthalate (PET), polyether sulfone (PES), polyethylene naphthalate (PEN), or polycarbonate (PC). For example, the resin used for the substrate 11 may have a property that makes it possible to resist processing temperatures at which respective elements to be described later are formed over the element-formation substrate 10. That is, for example, the resin used for the substrate 11 may have high-temperature heat resistance. For example, the

substrate 11 may be formed by applying a resin over a support base and causing the resin to cure. The substrate 11 may have a thickness of 10  $\mu\text{m}$ , for example.

[0030] The barrier films 12 and 13 suppress ingress of moisture into each element (to be described later) provided on the element-formation substrate 10. The barrier films 12 and 13 may each include, for example, an inorganic material, such as  $\text{SiO}_2$ , SiN, SiON,  $\text{Al}_2\text{O}_3$ , or SiO. The material of the barrier film 12 and the material of the barrier film 13 may be identical to or different from each other. The barrier film 12 may have a single-layer structure including an inorganic material, or may also have a stacked structure including inorganic materials. The barrier film 13 may have a single-layer structure including an inorganic material, or may also have a stacked structure including inorganic materials. The barrier film 12 may be, for example, a single-layer film including  $\text{SiO}_2$ , SiN, SiON,  $\text{Al}_2\text{O}_3$ , or SiO, or may also be, for example, a stacked film including two or more selected from the group consisting of  $\text{SiO}_2$ , SiN, SiON,  $\text{Al}_2\text{O}_3$ , and SiO. The barrier film 13 may be, for example, a single-layer film including  $\text{SiO}_2$ , SiN, SiON,  $\text{Al}_2\text{O}_3$ , or SiO, or may also be, for example, a stacked film including two or more selected from the group consisting of  $\text{SiO}_2$ , SiN, SiON,  $\text{Al}_2\text{O}_3$ , and SiO. The barrier films 12 and 13 may be formed by, for example, plasma-enhanced chemical vapor deposition (PECVD), atomic layer deposition (ALD), or sputtering. The barrier films 12 and 13 may have a thickness of less than 1  $\mu\text{m}$ , and the thickness may be in the range of more than or equal to 100 nm and less than or equal to 600 nm, for example.

[0031] Foreign substances can be mixed in the element-formation substrate 10 during a process of manufacturing the element-formation substrate 10. Non-limiting examples of the foreign substances that can be mixed in the element-formation substrate 10 include, as illustrated in FIG. 1, an organic foreign substance 110 and a metallic foreign substance 120. The organic foreign substance 110 and the metallic foreign substance 120 may be attached to a surface on which the barrier film 12 is provided (i.e., a top surface of the substrate 11) during a process of manufacturing the element-formation substrate 10. The organic foreign substance 110 may include, for example, plastics such as polyimide (PI), polyethylene terephthalate (PET), polyether sulfone (PES), polyethylene naphthalate (PEN), or polycarbonate (PC). The metallic foreign substance 120 may include, for example, metals such as stainless steel (SUS), aluminum (Al), iron (Fe), or copper (Cu).

[0032] The organic foreign substance 110 and the metallic foreign substance 120 may penetrate through the barrier film 12. A top surface of the organic foreign substance 110 may be leveled with a top surface of the barrier film 12, for example. A top part of the metallic foreign substance 120 may protrude from the barrier film 12, and a side surface of the top part of the metallic foreign substance 120 may be in a tapered shape. An organic part 15 may be attached around the top part of the metallic foreign substance 120. That is, in a case where the metallic foreign substance 120 having a part (top part) protruding from the barrier film 12 exists, the element-formation substrate 10 may include the organic part 15 attached around the part (top part) of the metallic foreign substance 120 protruding from the barrier film 12. In one embodiment of the disclosure, the organic part 15 corresponds to a specific but non-limiting example of a "second organic part". The organic part 15 may join the surface of the

metallic foreign substance **120** with the surface of the barrier film **12** more smoothly compared to a case where the organic part **15** is not provided.

[0033] The organic part **15** may be provided at a boundary between the barrier film **12** and the barrier film **13**. It may be possible that the barrier film **12** has a crack **12A** during a process of manufacturing the barrier film **12**. The crack **12A** may penetrate through the barrier film **12**, but in some cases, the crack **12A** may not penetrate through the barrier film **12** and may be formed only on the top surface of the barrier film **12**. The crack **12A** may be filled with an organic part **14**. That is, in a case where the barrier film **12** has the crack **12A**, the element-formation substrate **10** may include the organic part **14** that fills the crack **12A**. In one embodiment of the disclosure, the organic part **14** corresponds to a specific but non-limiting example of a “first organic part”. The organic parts **14** and **15** may include, for example, a resin material that is common to a material of the substrate **11**. Note that the organic parts **14** and **15** may include a resin material that is different from a material of the substrate **11**.

#### [Manufacturing Method]

[0034] Next, a method of manufacturing the element-formation substrate **10** is described below. FIGS. 2A to 2D illustrate a process of manufacturing the element-formation substrate **10**. First, as illustrated in FIG. 2A, the substrate **11** may be formed by applying a resin over a support base and causing the resin to cure. Here, let us assume that foreign substances (the organic foreign substance **110** and the metallic foreign substance **120**) as illustrated in FIG. 2A, for example, are attached on the substrate **11**. In this case, the substrate **11** may include a resin material that is common to a material of the organic layer **16** to be formed later. Next, as illustrated in FIG. 2B, the barrier film **12** may be formed over the substrate **11** using PECVD, for example. In this example, the organic foreign substance **110** and the metallic foreign substance **120** penetrate through the barrier film **12**, and the crack **12A** occurs on the top surface of the barrier film **12**.

[0035] Next, as illustrated in FIG. 2C, the organic layer **16** may be formed over the barrier film **12**. In this case, for example, the organic layer **16** may be thick enough for the crack **12A** to be embedded therein. For example, the thickness of the organic layer **16** may be smaller than the thickness of the substrate **11**, and may also be smaller than or equal to the thickness of the barrier film **12**. In this case, the organic layer **16** may include a resin material that is common to a material of the substrate **11**. Next, the organic layer **16** may be decomposed and removed by ashing using  $O_2$ ,  $O_3$ ,  $N_2$ ,  $SiH_4$ , or  $NH_3$ , for example, until the top surface of the barrier film **12** is exposed. As a result, as illustrated in FIG. 2D, for example, the organic layer **16** may remain inside the crack **12A** and at or near the top part of the metallic foreign substance **120**. In FIG. 2D, the organic layer **16** remained inside the crack **12A** is expressed as the organic part **14**, and the organic layer **16** remained at or near the top part of the metallic foreign substance **120** is expressed as the organic part **15**. Further, a part of the organic foreign substance **110** exposed above the barrier film **12** may also be removed by the above-mentioned ashing, so that the top surface of the organic foreign substance **110** is leveled with the top surface of the barrier film **12**. This is because the organic foreign substance **110** and the organic layer **16** may each include an organic material, and the etching rate of the

organic foreign substance **110** is approximately the same as the etching rate of the organic layer **16** in the above-mentioned ashing.

[0036] Next, as illustrated in FIG. 1, the barrier film **13** may be formed by, for example, PECVD, over the entire top surface of the barrier film **12** including the organic parts **14** and **15**. The material of the barrier film **13** and the material of the barrier film **12** may be identical to or different from each other. In this case, the crack **12A** may be filled with the organic part **14**, and, the organic part **15** may be provided at or near the top part of the metallic foreign substance **120**, so as to cover a part of the side surface of the top part of the metallic foreign substance **120** exposed above the barrier film **12**. Further, the top surface of the organic foreign substance **110** may be leveled with the top surface of the barrier film **12**. Accordingly, the surface over which the barrier film **13** is formed is approximately flat. As a result, the barrier film **13** may have no such crack **12A** as the barrier film **12** has. In this manner, the element-formation substrate **10** may be formed.

[0037] Note that, in an example case illustrated in FIG. 3, where the organic layer **16** is formed to have a thickness smaller than the thickness of the substrate **11**, the ashing on the organic layer **16** may be omitted, or the organic layer **16** may be subjected to ashing to an extent that the top surface of the barrier film **12** is about to be exposed. Here, in a case where the barrier film **12** has the crack **12A**, the element-formation substrate **10** has the organic layer **16** (including the organic part **14**). The organic layer **16** fills the crack **12A**, and is provided between the barrier film **12** and the barrier film **13**. Further, in a case where the metallic foreign substance **120** having a part (top part) protruding from the barrier film **12** exists, the element-formation substrate **10** has the organic layer **16** (including the organic part **15**). The organic layer **16** covers the part (top part) of the metallic foreign substance **120** protruding from the barrier film **12**, and is provided between the barrier film **12** and the barrier film **13**.

[0038] Further, in an example case illustrated in FIG. 3, where the organic layer **16** is formed such that a thickness  $d_2$  of the organic layer **16** is smaller than or equal to a thickness  $d_1$  of the barrier film **12**, the ashing on the organic layer **16** may be omitted, or the organic layer **16** may be subjected to ashing to an extent that the top surface of the barrier film **12** is about to be exposed. Here, in a case where the barrier film **12** has the crack **12A**, the element-formation substrate **10** has the organic layer **16** (including the organic part **14**). The organic layer **16** fills the crack **12A**, and is provided between the barrier film **12** and the barrier film **13**. Further, in a case where the metallic foreign substance **120** having a part (top part) protruding from the barrier film **12** exists, the element-formation substrate **10** has the organic layer **16** (including the organic part **15**). The organic layer **16** covers the part (top part) of the metallic foreign substance **120** protruding from the barrier film **12**, and is provided between the barrier film **12** and the barrier film **13**.

[0039] FIGS. 4 and 5 each illustrate an example of a cross-sectional configuration of an organic EL display device **100** including the element-formation substrate **10**. In one embodiment of the disclosure, the organic EL display device **100** corresponds to a specific but non-limiting example of a “light-emitting display device”. FIG. 4 illustrates an example of a cross-sectional configuration of the organic EL display device **100** including the element-for-

mation substrate **10** illustrated in FIG. 1, and FIG. 5 illustrates an example of a cross-sectional configuration of the organic EL display device **100** including the element-formation substrate **10** illustrated in FIG. 3. The organic EL display device **100** illustrated in FIGS. 4 and 5 each have a pixel layer **20** and a sealing layer **30** which are stacked in the stated order on the element-formation substrate **10**. The organic EL display device **100** may be manufactured by stacking the pixel layer **20** and the sealing layer **30** in the stated order on the element-formation substrate **10**.

[0040] The pixel layer **20** includes an interlayer insulating film **20b** and a plurality of pixels **20a** provided within the interlayer insulating film **20b**. The interlayer insulating film **20b** may include, for example, SiO<sub>2</sub>, SiN, SiON, Al<sub>2</sub>O<sub>3</sub>, or SiO. Each pixel **20a** may include a TFT **21** formed on the element-formation substrate **10** (for example, the barrier film **13**) and an organic EL element **22** electrically connected to the TFT **21**. The TFT **21** may control a current that flows in the organic EL element **22** on the basis of an external control signal. The current controlled by the TFT **21** may flow through the organic EL element **22**. This may cause the organic EL element **22** to emit light. The sealing layer **30** may have a single-layer structure including a resin material such as epoxy resin or vinyl-based resin. Note that the sealing layer **30** may also have, for example, a stacked structure including an inorganic sealing film including SiN formed by PECVD or Al<sub>2</sub>O<sub>3</sub> formed by ALD, and an organic sealing film including acrylic resin or epoxy resin.

[Effects]

[0041] Next, effects of the organic EL display device **100** and a method of manufacturing the organic EL display device **100** according to one example embodiment are described below.

[0042] In a sheet-like organic EL display device, glass substrates at the back and front of the sheet-like organic EL display device may be generally omitted. Accordingly, it is important to shield external moisture as a countermeasure against dark spots. In a case where a single-layer barrier film is provided to shield external moisture, a defect such as a crack or a pinhole that occurs in the barrier film becomes a path for the external moisture. Accordingly, in order to prevent the defect from penetrating through the barrier film, it has been suggested that a plurality of barrier films be stacked. Even in the case of adopting the suggestion, a defect at an underlying layer can induce additional defect from the second layer onward, and thus it is not easy to suppress the defect of the barrier film. Further, it has been suggested that an organic film be provided between the stacked barrier films. In this case, induction of additional defect from the second layer onward is suppressed owing to a planarization effect achieved by the organic film. However, the organic film absorbs water during the manufacturing process, which can cause the moisture stored in the organic film to serve as a moisture supply source after the device is completed, causing dark spots to occur.

[0043] On the other hand, according to one example embodiment, the organic part **14** and the organic part **15** are formed locally between the barrier film **12** and the barrier film **13**. The organic part **14** fills the crack **12A** occurred in the barrier film **12**, and the organic part **15** is attached around a part of the metallic foreign substance **120** protruding from the barrier film **12**. This suppresses occurrence of a defect in the barrier film **13** caused by a defect occurred in the barrier

film **12**, which is an underlying layer. Moreover, since the organic parts **14** and **15** are provided only locally, the moisture stored in the organic parts **14** and **15** cannot serve as a moisture supply source that causes dark spots to occur after the device is completed. Accordingly, it is possible to further enhance the moisture resistance of the device compared to a currently available sheet-like organic EL display device.

[0044] Further, according to one example embodiment, in a manufacturing process, the organic layer **16** having a thickness smaller than a thickness of the substrate **11** is formed on the barrier film **12** that suppresses ingress of moisture, and the barrier film **13** that suppresses ingress of moisture is formed on a surface including the organic layer **16**. Accordingly, in a case where the crack **12A** occurs in the barrier film **12**, some of the organic layer **16** remains in the crack **12A**, and in a case where the metallic foreign substance **120** protrudes from the barrier film **12**, some of the organic layer **16** is attached around the part of the metallic foreign substance **120** protruding from the barrier film **12**. As a result, the surface over which the barrier film **13** is formed is approximately flat, and therefore, the crack **12A** which occurs in the barrier film **12** does not occur in the barrier film **13**. Additionally, since the organic layer **16** (the organic parts **14** and **15**) remains only locally, the moisture stored in the organic parts **14** and **15** cannot serve as a moisture supply source that causes dark spots to occur after the device is completed. Accordingly, it is possible to further enhance the moisture resistance of the device compared to a currently available sheet-like organic EL display device.

[0045] Further, according to one example embodiment, in a manufacturing process, in a case where the thickness of the organic layer **16** is smaller than the thickness of the substrate **11** or is smaller than or equal to the thickness of the barrier film **12**, the organic layer **16** is ashed until the top surface of the barrier film **12** is exposed or to an extent that the top surface of barrier film **12** is about to be exposed. Accordingly, in a case where the crack **12A** occurs in the barrier film **12**, some of the organic layer **16** remains in the crack **12A**, and in a case where the metallic foreign substance **120** protrudes from the barrier film **12**, some of the organic layer is attached around the part of the metallic foreign substance **120** protruding from the barrier film **12**. Moreover, the organic foreign substance **110** is removed by ashing. As a result, the surface over which the barrier film **13** is formed is approximately flat, and therefore, the crack **12A** which occurs in the barrier film **12** does not occur in the barrier film **13**. Additionally, since the volume of the organic layer **16** (the organic parts **14** and **15**) becomes smaller by ashing, the moisture stored in the organic layer **16** (the organic parts **14** and **15**) cannot serve as a moisture supply source that causes dark spots to occur after the device is completed. Accordingly, it is possible to further enhance the moisture resistance of the device compared to a currently available sheet-like organic EL display device.

[0046] Further, according to one example embodiment, in a manufacturing process, the organic layer **16** is formed on the barrier film **12** such that the thickness of the organic layer **16** is smaller than or equal to the thickness of the barrier film **12**. Therefore, the moisture stored in the organic parts **14** and **15** cannot serve as a moisture supply source that causes dark spots to occur after the device is completed. Accordingly, it

is possible to further enhance the moisture resistance of the device compared to a currently available sheet-like organic EL display device.

[0047] Further, according to one example embodiment, in a manufacturing process, the substrate **11** is formed by applying a resin to a support base and causing the resin to cure. Here, the organic layer **16** is a layer formed only for making the surface on which the barrier film **13** is formed approximately flat. Accordingly, in a case where the organic layer **16** includes a resin material that is common to a material of the substrate **11**, it is possible to form the organic layer **16** generally without any problems, even if the conditions for forming the organic layer **16** are made common to the conditions for forming the substrate **11**, the conditions excluding the film thickness. Therefore, according to one example embodiment, it is possible to manufacture the element-formation substrate **10** highly easily.

## 2. Modification Example of First Embodiment

[Configuration]

[0048] In any embodiment of the disclosure, the organic layer **16** illustrated in FIG. 5, for example, may be replaced with a plurality of island-shaped organic layers **17** illustrated in FIG. 6, for example. In this case, the plurality of island-shaped organic layers **17** may be respectively provided at regions that are opposed to the respective pixels **20a** in the element-formation substrate **10**. Each organic layer **17** may be provided on the barrier film **12**, and may be provided between the barrier film **12** and the barrier film **13**. For example, each organic layer **17** may be thick enough for a crack **12A** to be embedded therein. For example, each organic layer **17** may be smaller than the thickness of the substrate **11**, and may also be smaller than or equal to the thickness of the barrier film **12**. In this case, each organic layer **17** may include a resin material that is common to a material of the substrate **11**.

[Manufacturing Method]

[0049] Next, a method of manufacturing the organic EL display device **100** according to one modification example is described below. According to one modification example, the processes before forming the organic layer **16** on the barrier film **12** (FIG. 2C) may be the same as those in any embodiment of the disclosure. Accordingly, a process after forming the organic layer **16** on the barrier film **12** is described below. Note that the description is made below of a case where the organic layer **16** includes a photosensitive material.

[0050] After the organic layer **16** is formed on the barrier film **12**, the organic layer **16** may be formed into the plurality of island-shaped organic layers **17** by patterning as illustrated in FIG. 7, for example. In one example, the plurality of island-shaped organic layers **17** may be respectively provided at regions that are opposed to the respective pixels **20a**. In this case, the organic layer **17** that fills the crack **12A** and the organic layer **17** that covers the metallic foreign substance **120** may be formed at regions that are opposed to the respective pixels **20a**. After that, the barrier film **13** is formed on the surface including the organic layers **17** (for example, see FIG. 6).

[Effects]

[0051] Next, effects of the organic EL display device **100** according to one modification example are described below.

[0052] The organic EL display device **100** according to one modification example may have the plurality of island-shaped organic layers **17** respectively provided at regions that are opposed to the respective pixels **20a**. Accordingly, it is possible to suppress occurrence of a defect in each pixel **20a** in which a presence of a defect is apt to be troublesome. Therefore, it is possible to further enhance the moisture resistance compared to a currently available sheet-like organic EL display device.

[0053] In a process of manufacturing the organic EL display device **100** according to one modification example, an organic layer including a photosensitive material is formed as the organic layer **16**, the organic layer **16** is patterned, and the plurality of island-shaped organic layers **17** is formed. Further, the barrier film **13** is formed on a surface including the island-shaped organic layers **17**. Accordingly, it is possible to suppress occurrence of a defect in each pixel **20a** in which a presence of a defect is apt to be troublesome. Therefore, it is possible to further enhance the moisture resistance compared to a currently available sheet-like organic EL display device.

## 3. Second Embodiment

[Configuration]

[0054] FIG. 8 is a diagram illustrating an example of a cross-sectional configuration of an element-formation substrate **40** according to one example embodiment of the disclosure. The element-formation substrate **40** may be suitably used as a substrate for forming an element easily influenced by moisture. The element mentioned herein refers to an element whose characteristics are easily degraded due to ingress of moisture. Non-limiting examples of the element easily influenced by moisture include an organic EL element and an active element including an oxide semiconductor or low-temperature polycrystalline silicon.

[0055] The element-formation substrate **40** has two barrier films **12** and **13** provided on a substrate **11**. A foreign substance can be mixed in the element-formation substrate **40** during a process of manufacturing an element-formation substrate **40**. Non-limiting examples of the foreign substance that can be mixed in the element-formation substrate **40** include, as illustrated in FIG. 8, an organic foreign substance **110** and a metallic foreign substance **130**. The organic foreign substance **110** and the metallic foreign substance **130** may be attached to a surface on which the barrier film **12** is provided (i.e., a top surface of the substrate **11**) during a process of manufacturing the element-formation substrate **40**.

[0056] The organic foreign substance **110** and the metallic foreign substance **130** may penetrate through the barrier film **12**. A top part of the organic foreign substance **110** may protrude from the barrier film **12**, and a side surface of the top part of the organic foreign substance **110** may be in a forward tapered shape. A top part of the metallic foreign substance **130** may protrude from the barrier film **12**, and a side surface of the top part of the metallic foreign substance **130** may be in an inversely tapered shape. An organic part **18** may be attached around the top part of the metallic

foreign substance **130**. The organic part **18** may be formed at a region which is hidden by the metallic foreign substance **130** when the metallic foreign substance **130** is viewed from above (i.e., a shade of the metallic foreign substance **130**). That is, in a case where the metallic foreign substance **130** having a part (top part) protruding from the barrier film **12** exists, the element-formation substrate **40** may include the organic part **18** attached around the part of the metallic foreign substance **130** protruding from the barrier film **12** (i.e., the shade of the metallic foreign substance **130**). The organic part **18** may include, for example, a resin material that is common to a material of the substrate **11**. Note that the organic part **18** may include a resin material that is different from a material of the substrate **11**. The organic part **18** may join the surface of the metallic foreign substance **130** with the surface of the barrier film **12** more smoothly compared to a case where the organic part **18** is not provided.

#### [Manufacturing Method]

**[0057]** Next, a method of manufacturing the element-formation substrate **40** is described below. Note that a process is hereinafter described of a case where the organic part **18** and an organic layer **19** (to be described later) each include a photosensitive material. FIGS. **9A** and **9B** illustrate a process of manufacturing the element-formation substrate **40**. First, the substrate **11** may be formed by applying a resin over a support base and causing the resin to cure. Here, let us assume that foreign substances (the organic foreign substance **110** and the metallic foreign substance **130**), for example, are attached on the substrate **11**. In this case, the substrate **11** may include a resin material that is common to a material of the organic layer **19** to be formed later. Next, the barrier film **12** may be formed over the substrate **11** using PECVD, for example. In this example, the organic foreign substance **110** and the metallic foreign substance **130** penetrate through the barrier film **12**, and a crack **12A** occurs on the top surface of the barrier film **12**.

**[0058]** Next, as illustrated in FIG. **9A**, the organic layer **19** may be formed over the barrier film **12**. In this case, for example, the organic layer **19** may be thick enough for the crack **12A** to be embedded therein. For example, the thickness of the organic layer **19** may be smaller than the thickness of the substrate **11**, and may also be smaller than or equal to the thickness of the barrier film **12**. In this case, the organic layer **19** may include a resin material that is common to a material of the substrate **11**. Next, the organic layer **19** may be subjected to exposing and developing directly (i.e., without using a mask), for example. As a result, as illustrated in FIG. **9B**, for example, the organic layer **19** may remain around the top part of the metallic foreign substance **130** (i.e., a shade of the metallic foreign substance **130**). In FIG. **9B**, the organic layer **19** remained around the top part of the metallic foreign substance **130** (i.e., a shade of the metallic foreign substance **130**) is expressed as the organic part **18**.

**[0059]** Next, as illustrated in FIG. **8**, the barrier film **13** may be formed by using, for example, PECVD, over the top surface including the organic part **18** (in one example, an entire top surface of the barrier film **12** including the organic part **18**). At or near the top part of the metallic foreign substance **130**, a part of the side surface of the top part of the metallic foreign substance **130** exposed above the barrier film **12** is covered with the organic part **18**. Accordingly, the

surface over which the barrier film **13** is formed is approximately flat. As a result, the barrier film **13** may have no such crack **12A** as the barrier film **12** has. In this manner, the element-formation substrate **40** may be formed.

**[0060]** FIG. **10** illustrates an example of a cross-sectional configuration of an organic EL display device **200** including the element-formation substrate **40**. FIG. **10** illustrates an example of a cross-sectional configuration of the organic EL display device **200** including the element-formation substrate **40** illustrated in FIG. **8**. The organic EL display device **200** illustrated in FIG. **10** has a pixel layer **20** and a sealing layer **30** which are stacked in the stated order on the element-formation substrate **40**. The organic EL display device **200** is manufactured by stacking the pixel layer **20** and the sealing layer **30** in the stated order on the element-formation substrate **40**.

#### [Effects]

**[0061]** Next, effects of the organic EL display device **200** and a method of manufacturing the organic EL display device **200** according to one example embodiment are described below.

**[0062]** According to one example embodiment, locally formed between the barrier film **12** and the barrier film **13** may be the organic part **18** attached around a part of the metallic foreign substance **130** protruding from the barrier film **12**. This suppresses occurrence of a defect in the barrier film **13** caused by a defect occurred in the barrier film **12**, which is an underlying layer. Moreover, since the organic part **18** is provided only locally, the moisture stored in the organic part **18** cannot serve as a moisture supply source that causes dark spots to occur after the device is completed. Accordingly, it is possible to further enhance the moisture resistance of the device compared to a currently available sheet-like organic EL display device.

**[0063]** Although the disclosure is described hereinabove with reference to the example embodiments and modification examples, these embodiments and modification examples are not to be construed as limiting the scope of the disclosure and may be modified in a wide variety of ways. It should be appreciated that the effects described herein are mere examples. Effects of an example embodiment and modification examples of the disclosure are not limited to those described herein. The disclosure may further include any effects other than those described herein.

**[0064]** It is possible to achieve at least the following configurations from the above-described example embodiments of the disclosure.

(1) A method of manufacturing a light-emitting display device, the method including:

**[0065]** forming a first barrier film on a substrate, the first barrier film suppressing ingress of moisture;

**[0066]** forming an organic layer on the first barrier film, the organic layer having a thickness smaller than a thickness of the substrate; and

**[0067]** forming a second barrier film on a surface including the organic layer, the second barrier film suppressing ingress of moisture.

(2) The method of manufacturing the light-emitting display device according to (1), in which upon forming the organic layer, the organic layer is ashed until a top surface of the first barrier film is exposed or to an extent that the top surface of the first barrier film is about to be exposed.

(3) The method of manufacturing the light-emitting display device according to (1) or (2), in which, upon forming the organic layer on the first barrier film, the organic layer is formed to have a thickness smaller than or equal to a thickness of the first barrier film.

(4) The method of manufacturing the light-emitting display device according to (1), in which,

**[0068]** upon forming the organic layer, the organic layer includes a photosensitive material, the organic layer is patterned, and a plurality of island-shaped organic layers is formed, and

**[0069]** upon forming the second barrier film, the second barrier film is formed on a surface including the island-shaped organic layers.

(5) The method of manufacturing the light-emitting display device according to (1), in which,

**[0070]** upon forming the organic layer, the organic layer includes a photosensitive material, the organic layer is directly exposed and developed, and an organic part is formed at a shade of a foreign substance, and,

**[0071]** upon forming the second barrier film, the second barrier film is formed on a surface including the organic part.

(6) The method of manufacturing the light-emitting display device according to any one of (1) to (5), in which, upon forming the first barrier film, the substrate is formed by applying a resin to a support base and causing the resin to cure.

(7) The method of manufacturing the light-emitting display device according to any one of (1) to (6), in which, upon forming the organic layer, the organic layer is formed using a resin material that is common to a material of the substrate.

(8) A light-emitting display device including:

**[0072]** an element-formation substrate including a first barrier film and a second barrier film provided on a substrate, the first barrier film and the second barrier film being provided in the stated order from the substrate and suppressing ingress of moisture; and

**[0073]** a plurality of pixels provided on the element-formation substrate,

**[0074]** the element-formation substrate further including an organic part that fills a crack occurred in the first barrier film, or that is attached around a part of a metallic foreign substance, the part of the metallic foreign substance protruding from the first barrier film.

(9) A light-emitting display device including:

**[0075]** an element-formation substrate including a first barrier film and a second barrier film provided on a substrate, the first barrier film and the second barrier film being provided in the stated order from the substrate and suppressing ingress of moisture; and

**[0076]** a plurality of pixels provided on the element-formation substrate,

**[0077]** the element-formation substrate including an organic layer that fills a crack occurred in the first barrier film, or that covers a part of a metallic foreign substance, the part of the metallic foreign substance protruding from the first barrier film, the organic layer being provided between the first barrier film and the second barrier film.

(10) The light-emitting display device according to (9), in which the organic layer is provided at a region that is opposed to each of the plurality of pixels.

(11) The light-emitting display device according to any one of (8) to (10), in which the substrate includes any one of polyimide, polyethylene terephthalate, polyether sulfone, polyethylene naphthalate, or polycarbonate.

(12) The light-emitting display device according to any one of (8) to (11), in which the first barrier film includes any one of  $\text{SiO}_2$ , SiN, SiON,  $\text{Al}_2\text{O}_3$ , or SiO.

(13) The light-emitting display device according to any one of (8) to (11), in which the first barrier film includes a stacked film including two or more selected from the group consisting of  $\text{SiO}_2$ , SiN, SiON,  $\text{Al}_2\text{O}_3$ , and SiO.

(14) The light-emitting display device according to (10), in which the organic layer has an island shape.

(15) The light-emitting display device according to (8), in which a top part of the metallic foreign substance is in contact with the second barrier film.

**[0078]** According to the method of manufacturing the light-emitting display device according to an example embodiment of the disclosure, the organic layer is provided on the first barrier film provided on the substrate. The organic layer has the thickness smaller than the thickness of the substrate, and the second barrier film is provided on the surface including the organic layer. The second barrier film suppresses ingress of moisture. This allows moisture resistance to be further enhanced.

**[0079]** According to the light-emitting display device according to an example embodiment of the disclosure, the organic part is further included. The organic part fills a crack occurred in the first barrier film, or that is attached around a part of a metallic foreign substance, the part of the metallic foreign substance protruding from the first barrier film. This allows moisture resistance to be further enhanced.

**[0080]** According to the light-emitting display device according to an example embodiment of the disclosure, the organic layer is further included. The organic layer fills a crack occurred in the first barrier film, or that covers a part of a metallic foreign substance, the part of the metallic foreign substance protruding from the first barrier film. The organic layer is provided between the first barrier film and the second barrier film. This allows moisture resistance to be further enhanced.

**[0081]** Note that the effects described herein are not necessarily limitative, and may be any effects described in the disclosure.

**[0082]** Although the technology has been described in terms of exemplary embodiments, this disclosure is not limited thereto. One of ordinary skill in the art would appreciate that variations may be made in the described embodiments by persons skilled in the art without departing from the scope of the technology as defined by the following claims. The limitations in the claims are to be interpreted broadly based on the language employed in the claims and not limited to examples described in this specification or during the prosecution of the application, and the examples are to be construed as non-exclusive. The use of the terms first, second, etc. do not denote any order or importance, but rather the terms first, second, etc. are used to distinguish one element from another. The term “substantially” and its variations are defined as being largely but not necessarily wholly what is specified as understood by one of ordinary skill in the art. The term “about” or “approximately” as used herein can allow for a degree of variability in a value or range. Moreover, no element or component in this disclosure

is intended to be dedicated to the public regardless of whether the element or component is explicitly recited in the following claims.

What is claimed is:

1. A light-emitting display device comprising:

an element-formation substrate including a first barrier film and a second barrier film provided on a substrate, the first barrier film and the second barrier film being provided in the stated order from the substrate and suppressing ingress of moisture; and

a plurality of pixels provided on the element-formation substrate,

the element-formation substrate further including an organic part that fills a crack occurred in the first barrier film, or that is attached around a part of a metallic foreign substance, the part of the metallic foreign substance protruding from the first barrier film.

2. A light-emitting display device comprising:

an element-formation substrate including a first barrier film and a second barrier film provided on a substrate, the first barrier film and the second barrier film being provided in the stated order from the substrate and suppressing ingress of moisture; and

a plurality of pixels provided on the element-formation substrate,

the element-formation substrate including an organic layer that fills a crack occurred in the first barrier film,

or that covers a part of a metallic foreign substance, the part of the metallic foreign substance protruding from the first barrier film, the organic layer being provided between the first barrier film and the second barrier film.

3. The light-emitting display device according to claim 2, wherein the organic layer is provided at a region that is opposed to each of the plurality of pixels.

4. The light-emitting display device according to claim 1, wherein the substrate comprises any one of polyimide, polyethylene terephthalate, polyether sulfone, polyethylene naphthalate, or polycarbonate.

5. The light-emitting display device according to claim 1, wherein the first barrier film comprises any one of  $\text{SiO}_2$ , SiN, SiON,  $\text{Al}_2\text{O}_3$ , or SiO.

6. The light-emitting display device according to claim 1, wherein the first barrier film comprises a stacked film including two or more selected from the group consisting of  $\text{SiO}_2$ , SiN, SiON,  $\text{Al}_2\text{O}_3$ , and SiO.

7. The light-emitting display device according to claim 3, wherein the organic layer has an island shape.

8. The light-emitting display device according to claim 1, wherein a top part of the metallic foreign substance is in contact with the second barrier film.

\* \* \* \* \*

专利名称(译)	显示装置		
公开(公告)号	<a href="#">US20200035947A1</a>	公开(公告)日	2020-01-30
申请号	US16/521699	申请日	2019-07-25
申请(专利权)人(译)	JOLED INC.		
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IPC分类号	H01L51/52 H01L51/00 C23C16/513 C23C16/34 C23C16/40		
CPC分类号	C23C16/513 C23C16/402 C23C16/403 H01L51/5253 H01L51/0097 C23C16/345 H01L51/56 H01L51/0096		
优先权	2018141797 2018-07-27 JP		
外部链接	<a href="#">Espacenet</a> <a href="#">USPTO</a>		

摘要(译)

发光显示装置包括元件形成基板和多个像素。元件形成基板包括设置在基板上的第一阻挡膜和第二阻挡膜，第一阻挡膜和第二阻挡膜从基板以规定的顺序设置并且抑制水分的侵入。在元件形成基板上设置多个像素。元件形成基板还包括有机部分，该有机部分填充在第一阻挡膜中发生的裂缝，或者附着在从第一阻挡膜突出的金属异物的一部分周围。

